

Product Bulletin Document #: PB22377Z

Document #: PB22377Z Issue Date: 19 July 2018

Title of Change:	Datasheet Update for LC75760UJA-AH.				
Effective date:	30 July 2018				
Contact information:	Contact your local ON Semiconductor Sales Office or < <u>Tetsuya.Tokunaga@onsemi.com</u> >				
Type of notification:	This Product Bulletin is for notification purposes only. ON Semiconductor will proceed with implementation of this change upon publication of this Product Bulletin.				
Change Category:	☐ Wafer Fab ☐ Assembly Change ☐ Test Change ☐ Other Datasheet Update				
☐ Manufacturing Site Transfer ☐ Product specific change			✓ Datasheet/Product Doc change✓ Shipping/Packaging/Marking✓ Other:		
Sites Affected:	ON Semiconductor Sites: None		External Foundry/Subcon Sites: None		
Description and Purpose:					
This PB is being issued to update the Datasheet of LC75760UJA-AH with adding specification in Allowable Power Dissipation.					
There is no change to the product form, fit, and function: Current Datasheet					
Parameter	Symbol	Condi	tions	Ratings	Unit
Allowable power dissipation Pd	max1 max2 max3	$Ta = +25^{\circ}C$ with PCE $Ta = +95^{\circ}C$ with PCE	B (Note 5) B (Note 5) B (Note 5)	1200	mW
Note 5: The PCB is a glass-epoxy board of 76.2 mm x 114.3 mm x 1.6 mm with 2 layers. Updated Datasheet					
Parameter	Symbol max1	Condi Ta = +25°C with PCE	tions 3 (Note 5)	Ratings 1200	Unit
Allowable power dissipation Pd Pd Pd Pd Pd	max2 max3 max4 max5 max6	$Ta = +95^{\circ}C$ with PCE $Ta = +105^{\circ}C$ with PCE $Ta = +25^{\circ}C$ with PCE $Ta = +95^{\circ}C$ with PCE	3 (Note 5)	528 430 2000 880 720) mW
Note 5: The PCB is a glass-epoxy board of 76.2 mm x 114.3 mm x 1.6 mm with 2 layers. Note 6: The PCB is a glass-epoxy board of 76.2 mm x 114.3 mm x 1.6 mm with 4 layers.					
List of Affected Part:					
LC75760UJA-AH					

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